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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	359200
Number of Logic Elements/Cells	952000
Total RAM Bits	53248000
Number of I/O	696
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-HBGA (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxeabk1h40c2l

Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering (1), (2), (3) (Part 2 of 2)

Transceiver Speed Grade	Core Speed Grade							
	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L	I3YY	I4
3 GX channel—8.5 Gbps	—	Yes	Yes	Yes	—	Yes	Yes (4)	Yes

Notes to Table 1:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

(3) C2L, I2L, and I3L speed grades are for low-power devices.

(4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering (1), (2)

Transceiver Speed Grade	Core Speed Grade			
	C1	C2	I2	I3
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	—	—
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes

Notes to Table 2:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.

CAUTION

Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)

Symbol	Description	Minimum	Maximum	Unit
V_{CC}	Power supply for core voltage and periphery circuitry	–0.5	1.35	V
V_{CCPT}	Power supply for programmable power technology	–0.5	1.8	V
V_{CCPGM}	Power supply for configuration pins	–0.5	3.9	V
V_{CC_AUX}	Auxiliary supply for the programmable power technology	–0.5	3.4	V
V_{CCBAT}	Battery back-up power supply for design security volatile key register	–0.5	3.9	V
V_{CCPD}	I/O pre-driver power supply	–0.5	3.9	V
V_{CCIO}	I/O power supply	–0.5	3.9	V

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Symbol	Description	Condition	Min (4)	Typ	Max (4)	Unit
t_{RAMP}	Power supply ramp time	Standard POR	200 µs	—	100 ms	—
		Fast POR	200 µs	—	4 ms	—

Notes to Table 6:

(1) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.

(2) If you do not use the design security feature in Stratix V devices, connect V_{CCBAT} to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V_{CCBAT}. Stratix V devices will not exit POR if V_{CCBAT} stays at logic low.

(3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.

(4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum (4)	Typical	Maximum (4)	Unit
V_{CCA_GXBL} (1), (3)	Transceiver channel PLL power supply (left side)	GX, GS, GT	2.85	3.0	3.15	V
			2.375	2.5	2.625	
V_{CCA_GXBR} (1), (3)	Transceiver channel PLL power supply (right side)	GX, GS	2.85	3.0	3.15	V
			2.375	2.5	2.625	
V_{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V
V_{CCHIP_L}	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V_{CCHIP_R}	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V_{CCHSSI_L}	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V_{CCHSSI_R}	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V_{CCR_GXBL} (2)	Receiver analog power supply (left side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)

Symbol	Description	Devices	Minimum (4)	Typical	Maximum (4)	Unit
V_{CCR_GXBR} (2)	Receiver analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
V_{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V_{CCT_GXBL} (2)	Transmitter analog power supply (left side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
V_{CCT_GXBR} (2)	Transmitter analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
V_{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V_{CCL_GTBR}	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V_{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V_{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

Notes to Table 7:

(1) This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

(2) Refer to Table 8 to select the correct power supply level for your design.

(3) When using ATX PLLs, the supply must be 3.0 V.

(4) This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) (1)

Symbol	Description	V_{CCIO} (V)	Typical	Unit
dR/dT	OCT variation with temperature without recalibration	3.0	0.189	%/°C
		2.5	0.208	
		1.8	0.266	
		1.5	0.273	
		1.2	0.317	

Note to Table 13:

(1) Valid for a V_{CCIO} range of ±5% and a temperature range of 0° to 85°C.

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Description	Value	Unit
C_{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C_{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C_{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	pF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
$I_{IOPIN\ (DC)}$	DC current per I/O pin	300 µA
$I_{IOPIN\ (AC)}$	AC current per I/O pin	8 mA (1)
$I_{XCVR\text{-}TX\ (DC)}$	DC current per transceiver transmitter pin	100 mA
$I_{XCVR\text{-}RX\ (DC)}$	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C\ dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

Internal Weak Pull-Up Resistor

Table 16 lists the weak pull-up resistor values for Stratix V devices.

Table 16. Internal Weak Pull-Up Resistor for Stratix V Devices (1), (2)

Symbol	Description	V_{CCIO} Conditions (V) (3)	Value (4)	Unit
R_{PU}	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option.	3.0 ±5%	25	kΩ
		2.5 ±5%	25	kΩ
		1.8 ±5%	25	kΩ
		1.5 ±5%	25	kΩ
		1.35 ±5%	25	kΩ
		1.25 ±5%	25	kΩ
		1.2 ±5%	25	kΩ

Notes to Table 16:

(1) All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins.

(2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 kΩ.

(3) The pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.

(4) These specifications are valid with a ±10% tolerance to cover changes over PVT.

I/O Standard Specifications

Table 17 through Table 22 list the input voltage (V_{IH} and V_{IL}), output voltage (V_{OH} and V_{OL}), and current drive characteristics (I_{OH} and I_{OL}) for various I/O standards supported by Stratix V devices. These tables also show the Stratix V device family I/O standard specifications. The V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL}, respectively.

For an explanation of the terms used in Table 17 through Table 22, refer to "Glossary" on page 65. For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012_486.

Table 17. Single-Ended I/O Standards for Stratix V Devices

I/O Standard	V_{CCIO} (V)			V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
LVTTL	2.85	3	3.15	–0.3	0.8	1.7	3.6	0.4	2.4	2	–2
LVCMOS	2.85	3	3.15	–0.3	0.8	1.7	3.6	0.2	V_{CCIO} – 0.2	0.1	–0.1
2.5 V	2.375	2.5	2.625	–0.3	0.7	1.7	3.6	0.4	2	1	–1
1.8 V	1.71	1.8	1.89	–0.3	0.35 * V_{CCIO}	0.65 * V_{CCIO}	V_{CCIO} + 0.3	0.45	V_{CCIO} – 0.45	2	–2
1.5 V	1.425	1.5	1.575	–0.3	0.35 * V_{CCIO}	0.65 * V_{CCIO}	V_{CCIO} + 0.3	0.25 * V_{CCIO}	0.75 * V_{CCIO}	2	–2
1.2 V	1.14	1.2	1.26	–0.3	0.35 * V_{CCIO}	0.65 * V_{CCIO}	V_{CCIO} + 0.3	0.25 * V_{CCIO}	0.75 * V_{CCIO}	2	–2

Table 18. Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Stratix V Devices

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 * V_{CCIO}	0.5 * V_{CCIO}	0.51 * V_{CCIO}	V_{REF} – 0.04	V_{REF}	V_{REF} + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V_{REF} – 0.04	V_{REF}	V_{REF} + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 * V_{CCIO}	0.5 * V_{CCIO}	0.51 * V_{CCIO}	0.49 * V_{CCIO}	0.5 * VCCIO	0.51 * V_{CCIO}
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 * V_{CCIO}	0.5 * V_{CCIO}	0.51 * V_{CCIO}	0.49 * V_{CCIO}	0.5 * V_{CCIO}	0.51 * V_{CCIO}
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 * V_{CCIO}	0.5 * V_{CCIO}	0.51 * V_{CCIO}	0.49 * V_{CCIO}	0.5 * VCCIO	0.51 * V_{CCIO}
SSTL-12 Class I, II	1.14	1.20	1.26	0.49 * V_{CCIO}	0.5 * V_{CCIO}	0.51 * V_{CCIO}	0.49 * V_{CCIO}	0.5 * VCCIO	0.51 * V_{CCIO}
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	V_{CCIO}/2	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	V_{CCIO}/2	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 * V_{CCIO}	0.5 * V_{CCIO}	0.53 * V_{CCIO}	—	V_{CCIO}/2	—
HSUL-12	1.14	1.2	1.3	0.49 * V_{CCIO}	0.5 * V_{CCIO}	0.51 * V_{CCIO}	—	—	—

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 1 of 2)

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	V_{OL} (V)	V_{OH} (V)	I_{ol} (mA)	I_{oh} (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	–0.3	V_{REF} – 0.15	V_{REF} + 0.15	V_{CCIO} + 0.3	V_{REF} – 0.31	V_{REF} + 0.31	V_{TT} – 0.608	V_{TT} + 0.608	8.1	–8.1
SSTL-2 Class II	–0.3	V_{REF} – 0.15	V_{REF} + 0.15	V_{CCIO} + 0.3	V_{REF} – 0.31	V_{REF} + 0.31	V_{TT} – 0.81	V_{TT} + 0.81	16.2	–16.2
SSTL-18 Class I	–0.3	V_{REF} – 0.125	V_{REF} + 0.125	V_{CCIO} + 0.3	V_{REF} – 0.25	V_{REF} + 0.25	V_{TT} – 0.603	V_{TT} + 0.603	6.7	–6.7
SSTL-18 Class II	–0.3	V_{REF} – 0.125	V_{REF} + 0.125	V_{CCIO} + 0.3	V_{REF} – 0.25	V_{REF} + 0.25	0.28	V_{CCIO} – 0.28	13.4	–13.4
SSTL-15 Class I	—	V_{REF} – 0.1	V_{REF} + 0.1	—	V_{REF} – 0.175	V_{REF} + 0.175	0.2 * V_{CCIO}	0.8 * V_{CCIO}	8	–8
SSTL-15 Class II	—	V_{REF} – 0.1	V_{REF} + 0.1	—	V_{REF} – 0.175	V_{REF} + 0.175	0.2 * V_{CCIO}	0.8 * V_{CCIO}	16	–16
SSTL-135 Class I, II	—	V_{REF} – 0.09	V_{REF} + 0.09	—	V_{REF} – 0.16	V_{REF} + 0.16	0.2 * V_{CCIO}	0.8 * V_{CCIO}	—	—
SSTL-125 Class I, II	—	V_{REF} – 0.85	V_{REF} + 0.85	—	V_{REF} – 0.15	V_{REF} + 0.15	0.2 * V_{CCIO}	0.8 * V_{CCIO}	—	—
SSTL-12 Class I, II	—	V_{REF} – 0.1	V_{REF} + 0.1	—	V_{REF} – 0.15	V_{REF} + 0.15	0.2 * V_{CCIO}	0.8 * V_{CCIO}	—	—

Table 24 shows the maximum transmitter data rate for the clock network.

Table 24. Clock Network Maximum Data Rate Transmitter Specifications *(1)*

Clock Network	ATX PLL			CMU PLL *(2)*			fPLL		
	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 *(3)*	14.1	—	6	12.5	—	6	3.125	—	3
x6 *(3)*	—	14.1	6	—	12.5	6	—	3.125	6
x6 PLL Feedback *(4)*	—	14.1	Side-wide	—	12.5	Side-wide	—	—	—
xN (PCIe)	—	8.0	8	—	5.0	8	—	—	—
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above and below PLL	3.125	3.125	Up to 13 channels above and below PLL
	—	8.01 to 9.8304	Up to 7 channels above and below PLL						

Notes to Table 24:

(1) Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.

(2) ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

(3) Channel span is within a transceiver bank.

(4) Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 of 5) (1)

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
t_{pll_lock} (14)	—	—	—	10	—	—	10	µs

Notes to Table 28:

(1) Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.

(2) The reference clock common mode voltage is equal to the VCCR_GXB power supply level.

(3) The device cannot tolerate prolonged operation at this absolute maximum.

(4) The differential eye opening specification at the receiver input pins assumes that receiver equalization is disabled. If you enable receiver equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

(5) Refer to Figure 5 for the GT channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.

(6) Refer to Figure 6 for the GT channel DC gain curves.

(7) CFP2 optical modules require the host interface to have the receiver data pins differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.

(8) Specifications for this parameter are the same as for Stratix V GX and GS devices. See Table 23 for specifications.

(9) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.

(10) t_{LTD} is time required for the receiver CDR to start recovering valid data after the `rx_is_lockedtodata` signal goes high.

(11) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the `rx_is_lockedtodata` signal goes high when the CDR is functioning in the manual mode.

(12) $t_{LTR\_LTD\_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the `rx_is_lockedtoref` signal goes high when the CDR is functioning in the manual mode.

(13) `tpll_powerdown` is the PLL powerdown minimum pulse width.

(14) `tpll_lock` is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.

(15) To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.

(16) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin - V_{ICM}).

(17) For ES devices, RREF is 2000 Ω ±1%.

(18) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).

(19) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.

(20) Refer to Figure 4.

(21) For oversampling design to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.

(22) This supply follows VCCR_GXB for both GX and GT channels.

(23) When you use fPLL as a TXPLL of the transceiver.

Table 29 shows the V_{OD} settings for the GT channel.

Table 29. Typical V_{OD} Setting for GT Channel, TX Termination = 100 Ω

Symbol	V_{OD} Setting	V_{OD} Value (mV)
V_{OD} differential peak to peak typical (1)	0	0
	1	200
	2	400
	3	600
	4	800
	5	1000

Note:

(1) Refer to Figure 4.

Figure 4 shows the differential transmitter output waveform.

Figure 4. Differential Transmitter/Receiver Output/Input Waveform

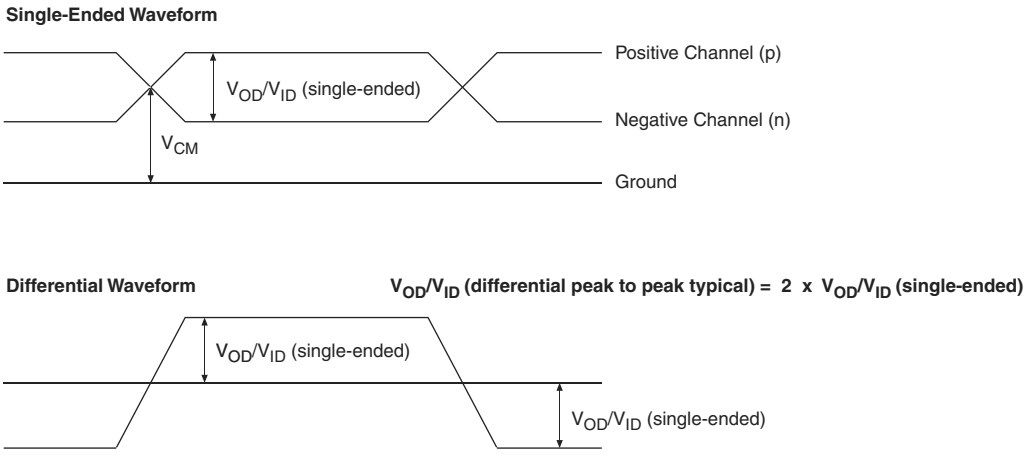


Figure 5 shows the Stratix V AC gain curves for GT channels.

Figure 5. AC Gain Curves for GT Channels

PLL Specifications

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85°C) and the industrial junction temperature range (–40° to 100°C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Typ	Max	Unit
f_{IN}	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	—	800 (1)	MHz
	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	—	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	—	650 (1)	MHz
f_{INPFD}	Input frequency to the PFD	5	—	325	MHz
f_{FINPFD}	Fractional Input clock frequency to the PFD	50	—	160	MHz
f_{VCO} (9)	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	—	1600	MHz
	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	—	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	—	1300	MHz
$t_{EINDUTY}$	Input clock or external feedback clock input duty cycle	40	—	60	%
f_{OUT}	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	—	—	717 (2)	MHz
	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	—	—	650 (2)	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	—	—	580 (2)	MHz
f_{OUT_EXT}	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	—	—	800 (2)	MHz
	Output frequency for an external clock output (C3, I3, I3L speed grades)	—	—	667 (2)	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	—	—	553 (2)	MHz
$t_{OUTDUTY}$	Duty cycle for a dedicated external clock output (when set to **50%**)	45	50	55	%
t_{FCOMP}	External feedback clock compensation time	—	—	10	ns
$f_{DYCONFIGCLK}$	Dynamic Configuration Clock used for `mgmt_clk` and `scanclk`	—	—	100	MHz
t_{LOCK}	Time required to lock from the end-of-device configuration or deassertion of `areset`	—	—	1	ms
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	1	ms
f_{CLBW}	PLL closed-loop low bandwidth	—	0.3	—	MHz
	PLL closed-loop medium bandwidth	—	1.5	—	MHz
	PLL closed-loop high bandwidth (7)	—	4	—	MHz
t_{PLL_PSERR}	Accuracy of PLL phase shift	—	—	±50	ps
t_{ARESET}	Minimum pulse width on the `areset` signal	10	—	—	ns

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)

Mode	Peformance							Unit
	C1	C2, C2L	I2, I2L	C3	I3, I3L, I3YY	C4	I4	
Modes using Three DSPs								
One complex 18 x 25	425	425	415	340	340	275	265	MHz
Modes using Four DSPs								
One complex 27 x 27	465	465	465	380	380	300	290	MHz

Memory Block Specifications

Table 33 lists the Stratix V memory block specifications.

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 1 of 2)

Memory	Mode	Resources Used		Performance							Unit
		ALUTs	Memory	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L, I3YY	I4	
MLAB	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz
	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz
	Simple dual-port, x16 depth (3)	0	1	675	675	533	400	675	533	400	MHz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 2 of 2)

Memory	Mode	Resources Used		Performance							Unit
		ALUTs	Memory	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L, I3YY	I4	
M20K Block	Single-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port with the read-during-write option set to **Old Data**, all supported widths	0	1	525	525	455	400	525	455	400	MHz
	Simple dual-port with ECC enabled, 512 × 32	0	1	450	450	400	350	450	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	600	600	500	450	600	500	450	MHz
	True dual port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	ROM, all supported widths	0	1	700	700	650	550	700	500	450	MHz

Notes to Table 33:

(1) To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.

(2) When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F_{MAX}.

(3) The F_{MAX} specification is only achievable with Fitter options, **MLAB Implementation In 16-Bit Deep Mode** enabled.

Temperature Sensing Diode Specifications

Table 34 lists the internal TSD specification.

Table 34. Internal Temperature Sensing Diode Specification

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
–40°C to 100°C	±8°C	No	1 MHz, 500 KHz	< 100 ms	8 bits	8 bits

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

Table 35. External Temperature Sensing Diode Specifications for Stratix V Devices

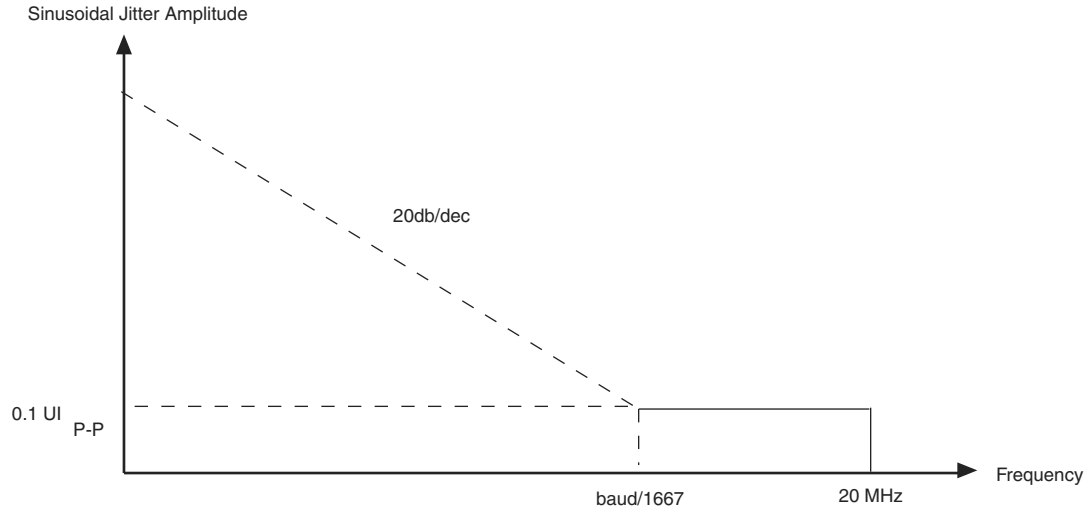
Description	Min	Typ	Max	Unit
I_{bias}, diode source current	8	—	200	μA
$V_{bias,}$ voltage across diode	0.3	—	0.9	V
Series resistance	—	—	< 1	Ω
Diode ideality factor	1.006	1.008	1.010	—

Table 38. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate ≥ 1.25 Gbps

Jitter Frequency (Hz)		Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

Figure 9 shows the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate < 1.25 Gbps.

Figure 9. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate < 1.25 Gbps



DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

Table 39. DLL Range Specifications for Stratix V Devices (1)

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

Note to Table 39:

(1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 1 of 2)

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 2 of 2)

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

Notes to Table 40:

(1) The typical value equals the average of the minimum and maximum values.

(2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a –2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is [625 ps + (10 × 10 ps) ± 20 ps] = 725 ps ± 20 ps.

Table 41 lists the DQS phase shift error for Stratix V devices.

Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Stratix V Devices (1)

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

Notes to Table 41:

(1) This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a –2 speed grade is ±78 ps or ±39 ps.

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (2), (3) (Part 1 of 2)

Clock Network	Parameter	Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
Regional	Clock period jitter	$t_{JIT(per)}$	–50	50	–50	50	–55	55	–55	55	ps
	Cycle-to-cycle period jitter	$t_{JIT(cc)}$	–100	100	–100	100	–110	110	–110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	–50	50	–50	50	–82.5	82.5	–82.5	82.5	ps
Global	Clock period jitter	$t_{JIT(per)}$	–75	75	–75	75	–82.5	82.5	–82.5	82.5	ps
	Cycle-to-cycle period jitter	$t_{JIT(cc)}$	–150	150	–150	150	–165	165	–165	165	ps
	Duty cycle jitter	$t_{JIT(duty)}$	–75	75	–75	75	–90	90	–90	90	ps

Duty Cycle Distortion (DCD) Specifications

Table 44 lists the worst-case DCD for Stratix V devices.

Table 44. Worst-Case DCD on Stratix V I/O Pins *(1)*

Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

Note to Table 44:

(1) The DCD numbers do not cover the core clock network.

Configuration Specification

POR Delay Specification

Power-on reset (POR) delay is defined as the delay between the time when all the power supplies monitored by the POR circuitry reach the minimum recommended operating voltage to the time when the nSTATUS is released high and your device is ready to begin configuration.

For more information about the POR delay, refer to the *Hot Socketing and Power-On Reset in Stratix V Devices* chapter.

Table 45 lists the fast and standard POR delay specification.

Table 45. Fast and Standard POR Delay Specification *(1)*

POR Delay	Minimum	Maximum
Fast	4 ms	12 ms
Standard	100 ms	300 ms

Note to Table 45:

(1) You can select the POR delay based on the MSEL settings as described in the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

JTAG Configuration Specifications

Table 46 lists the JTAG timing parameters and values for Stratix V devices.

Table 46. JTAG Timing Parameters and Values for Stratix V Devices

Symbol	Description	Min	Max	Unit
t_{JCP}	TCK clock period *(2)*	30	—	ns
t_{JCP}	TCK clock period *(2)*	167	—	ns
t_{JCH}	TCK clock high time *(2)*	14	—	ns
t_{JCL}	TCK clock low time *(2)*	14	—	ns
$t_{JPSU\ (TDI)}$	TDI JTAG port setup time	2	—	ns
$t_{JPSU\ (TMS)}$	TMS JTAG port setup time	3	—	ns

Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	µs
t_{STATUS}	nSTATUS low pulse width	268	1,506 (2)	µs
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 (3)	µs
t_{CF2CK} (6)	nCONFIG high to first rising edge on DCLK	1,506	—	µs
t_{ST2CK} (6)	nSTATUS high to first rising edge of DCLK	2	—	µs
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency (FPP ×8/×16)	—	125	MHz
	DCLK frequency (FPP ×32)	—	100	MHz
t_{CD2UM}	CONF_DONE high to user mode (4)	175	437	µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (8576 × CLKUSR period) (5)	—	—

Notes to Table 50:

(1) Use these timing parameters when the decompression and design security features are disabled.

(2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

(3) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

(4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

(5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

(6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is more than 1.

Table 53. AS Timing Parameters for AS ×1 and AS ×4 Configurations in Stratix V Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t_{CD2UM}	CONF_DONE high to user mode (3)	175	437	µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (8576 × CLKUSR period)	—	—

Notes to Table 53:

(1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

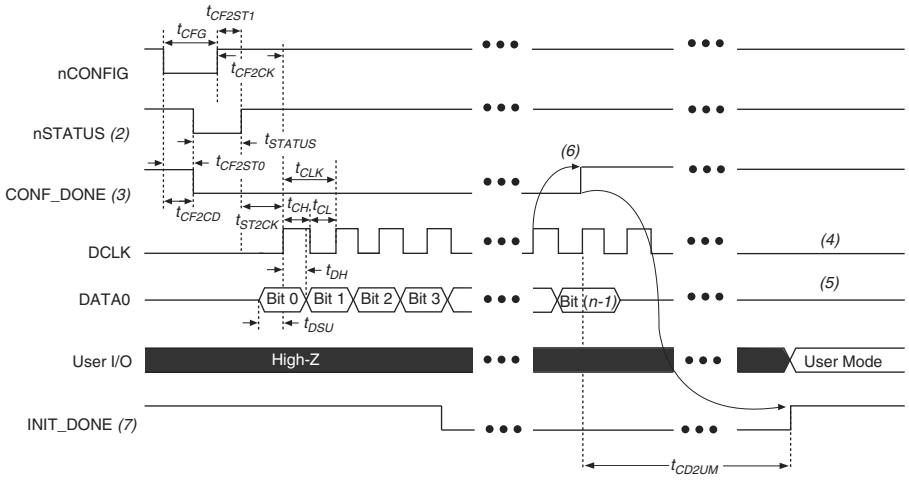
(2) t_{CF2CD}, t_{CF2ST0}, t_{CFG}, t_{STATUS}, and t_{CF2ST1} timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.

(3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform (1)



Notes to Figure 15:

(1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.

(2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.

(3) After power-up, before and during configuration, CONF_DONE is low.

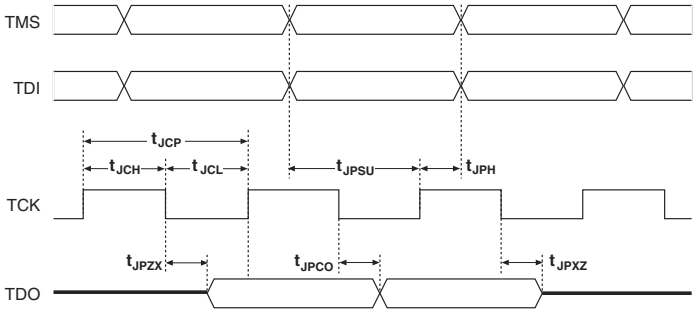
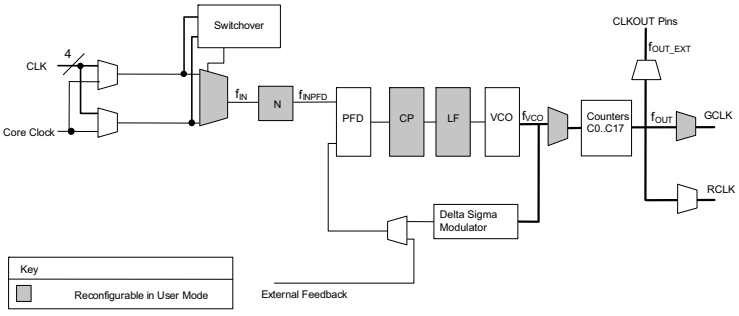
(4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.

(5) DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.

(6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.

(7) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G H I	—	—
J	J	High-speed I/O block—Deserialization factor (width of parallel data bus).
J	JTAG Timing Specifications	JTAG Timing Specifications: 
K L M N O	—	—
P	**PLL Specifications**	**Diagram of PLL Specifications** *(1)*  **Note:** (1) `Core Clock` can only be fed by dedicated clock input pins or PLL outputs.
Q	—	—
R	R_L	Receiver differential input discrete resistor (external to the Stratix V device).

Document Revision History

Table 61 lists the revision history for this chapter.

Table 61. Document Revision History (Part 1 of 3)

Date	Version	Changes
June 2018	3.9	■ Added the “Stratix V Device Overshoot Duration” figure.
April 2017	3.8	■ Added a footnote to the “High-Speed I/O Specifications for Stratix V Devices” table. ■ Changed the minimum value for t_{CD2UMC} in the “PS Timing Parameters for Stratix V Devices” table. ■ Changed the condition for 100-Ω R_D in the “OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices” table. ■ Changed the minimum value for t_{CD2UMC} in the “AS Timing Parameters for AS ´1 and AS ´4 Configurations in Stratix V Devices” table ■ Changed the minimum value for t_{CD2UMC} in the “FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1” table. ■ Changed the minimum value for t_{CD2UMC} in the “FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1” table. ■ Changed the minimum number of clock cycles value in the “Initialization Clock Source Option and the Maximum Frequency” table.
June 2016	3.7	■ Added the V_{ID} minimum specification for LVPECL in the “Differential I/O Standard Specifications for Stratix V Devices” table ■ Added the I_{OUT} specification to the “Absolute Maximum Ratings for Stratix V Devices” table.
December 2015	3.6	■ Added a footnote to the “High-Speed I/O Specifications for Stratix V Devices” table.
December 2015	3.5	■ Changed the transmitter, receiver, and ATX PLL data rate specifications in the “Transceiver Specifications for Stratix V GX and GS Devices” table. ■ Changed the configuration .rbf sizes in the “Uncompressed .rbf Sizes for Stratix V Devices” table.

July 2015	3.4	■ Changed the data rate specification for transceiver speed grade 3 in the following tables:
		  ■ “Transceiver Specifications for Stratix V GX and GS Devices”
		  ■ “Stratix V Standard PCS Approximate Maximum Date Rate”
		  ■ “Stratix V 10G PCS Approximate Maximum Data Rate”
		■ Changed the conditions for reference clock rise and fall time, and added a note to the “Transceiver Specifications for Stratix V GX and GS Devices” table.
		■ Added a note to the “Minimum differential eye opening at receiver serial input pins” specification in the “Transceiver Specifications for Stratix V GX and GS Devices” table.
		■ Changed the t_{CO} maximum value in the “AS Timing Parameters for AS ´1 and AS ´4 Configurations in Stratix V Devices” table.
		■ Removed the CDR ppm tolerance specification from the “Transceiver Specifications for Stratix V GX and GS Devices” table.